

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|--|------------------|---------|------------------|
| L4 | 24 | ("4804810" "4944447" "4986460" "5087590" "5188280" "5297333" "5427301" "5628110" "5648136" "5988481" "6013899" "6029427" "6053234" "6070780" "6092713" "6100496" "6131795" "6146920" "6158648" "6168669" "6182733" "6193459" "6226452" "6543131").PN. OR ("6818543").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/07 14:38 |
| S1 | 6 | "bottner, harald".in. and "schubert, axel".in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 09:28 |
| S2 | 6 | ((("6319617") or ("5320272") or ("4636073")).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/13 09:48 |
| S3 | 514 | (257/772).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/13 15:35 |
| S4 | 589 | solder and eutectic and gold and bismuth | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/07 10:08 |
| S5 | 33 | eutectic with (gold with bismuth) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 13:19 |
| S6 | 154 | peltier and eutectic | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 13:31 |

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| S7 | 434 | "laser diode" and eutectic | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 13:31 |
| S8 | 78 | (interdigitated same capacitor) and humidity | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 16:00 |
| S9 | 234 | "heat sink" with eutectic | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 15:12 |
| S10 | 23 | "photodiode" with eutectic | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 15:22 |
| S11 | 0 | "fluid cell" with eutectic | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 15:23 |
| S12 | 1 | "fluidic cell" and eutectic | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 15:24 |
| S13 | 1 | "fluidic cell" and solder | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 15:24 |
| S14 | 39 | "fluidic cell" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 15:35 |

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| S15 | 35 | (interdigitated same (capacitor or electrode)) and humidity and (solder) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 16:08 |
| S16 | 2279 | humidity near2 (sensor or sens\$3) and substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 16:08 |
| S17 | 98 | humidity near2 (sensor or sens\$3) and substrate and interdigitated | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/13 16:09 |
| S18 | 2 | ("5072262" "5546802").PN. OR ("6568265").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/13 16:19 |
| S19 | 6 | "fluidic cell" and peltier | US-PGPUB; USPAT; USOCR | OR | ON | 2005/07/13 16:20 |

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| S20 | 44 | (US-20010037681-\$ or US-20020024662-\$ or US-20020100972-\$ or US-20020179135-\$ or US-20030056571-\$ or US-20030075939-\$ or US-20030127333-\$ or US-20030202332-\$ or US-20040046223-\$ or US-20040067604-\$ or US-20040089945-\$ or US-20040188813-\$ or US-20040212094-\$ or US-20040238966-\$ or US-20040245611-\$ or US-20050110157-\$ or US-20050133572-\$).did. or (US-3607148-\$ or US-4651191-\$ or US-4915167-\$ or US-4947238-\$ or US-5040381-\$ or US-5542018-\$ or US-5596231-\$ or US-5736074-\$ or US-5854087-\$ or US-5966939-\$ or US-6077380-\$ or US-6108472-\$ or US-6153940-\$ or US-6159764-\$ or US-6281573-\$ or US-6327407-\$ or US-6344690-\$ or US-6455785-\$ or US-6486411-\$ or US-6548750-\$ or US-6550665-\$ or US-6568265-\$ or US-6680128-\$ or US-6740544-\$ or US-6774306-\$ or US-6786385-\$). did. or (US-6818543-\$).did. | US-PGPUB; USPAT | OR | ON | 2005/09/07 10:00 |
| S21 | 25 | S20 and gold and bismuth | US-PGPUB; USPAT | OR | ON | 2005/09/07 10:00 |
| S22 | 599 | solder and eutectic and gold and bismuth | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/07 10:08 |
| S23 | 364 | S22 and (layer with (thickness or thick)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/07 10:09 |
| S24 | 127 | S22 and (solder with layer with (thickness or thick)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/07 10:09 |